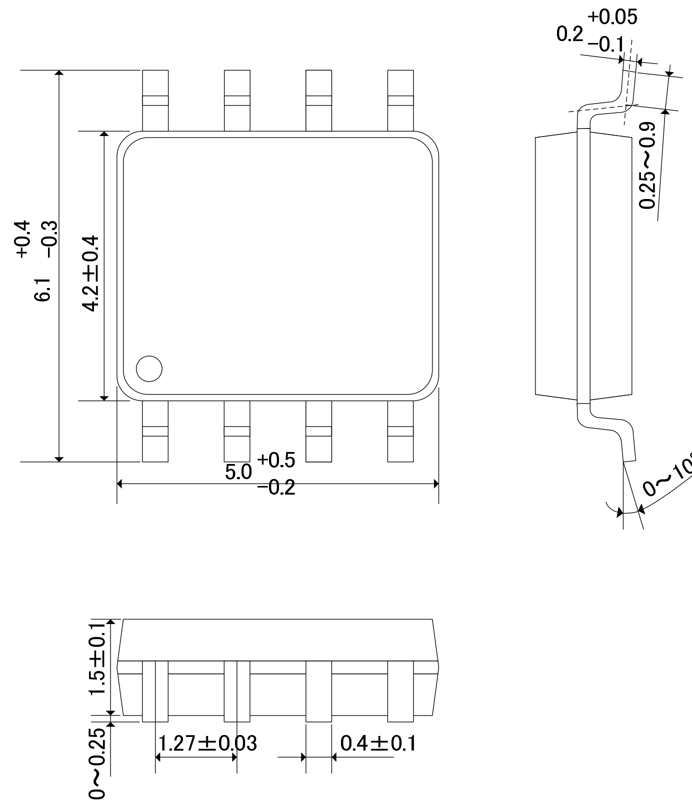
Packaging Information / Reference Pattern Layout Dimensions

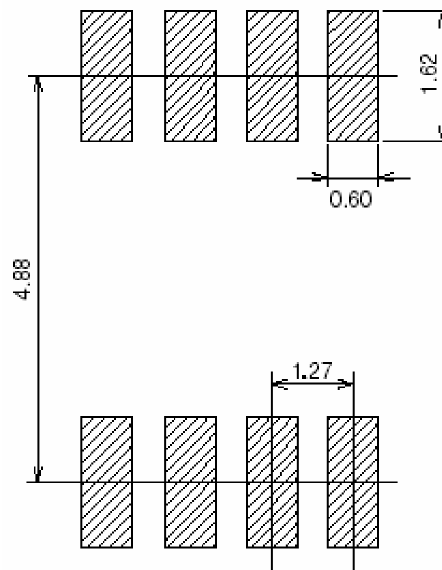
●SOP-8

Unit: mm

■Packaging Information



■Reference Pattern Layout Dimension

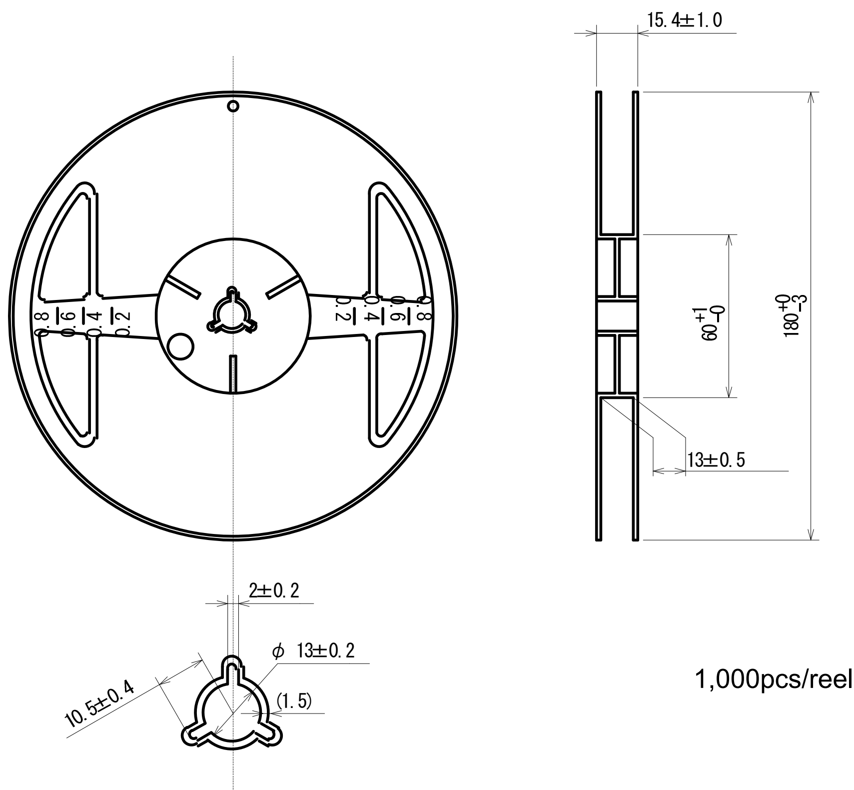


テーピング仕様 / Taping Specifications

SOP-8

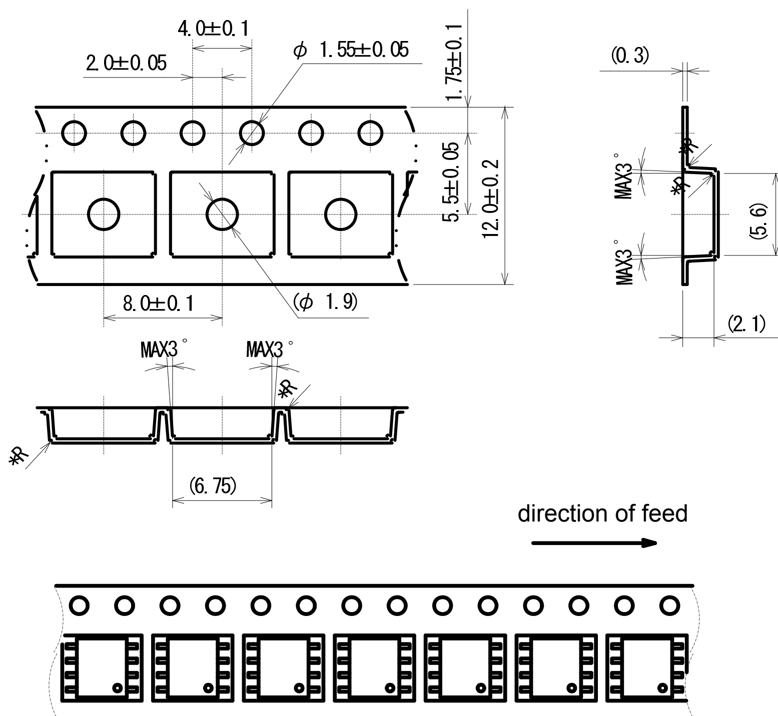
Unit: mm

●リール/Reel



1,000pcs/reel

●テーピング仕様/Taping Specifications



R Type :[Device orientation : Right]

Standard feed

●SOP-8 Power Dissipation

Power dissipation data for the SOP-8 is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as one of reference data taken in the described condition.

1. Measurement Condition (Reference data)

Condition : Mount on a board

Ambient : Natural convection

Soldering : Lead (Pb) free

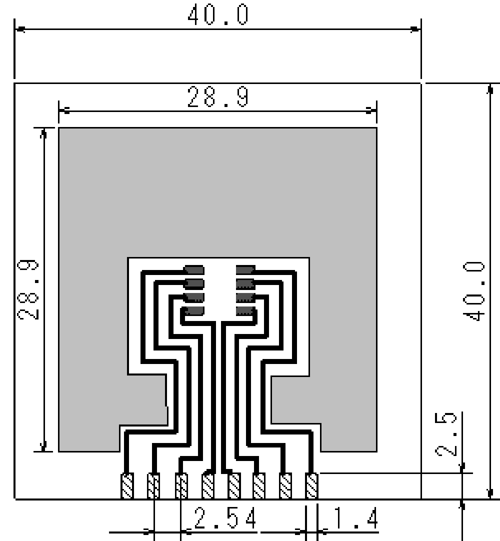
Board : Dimensions 40mm×40mm（1600mm^2 in one side）

Copper (Cu) traces occupy 50% of the board area

In top and back faces

Material : Glass Epoxy（FR-4）

Thickness : 1.6mm

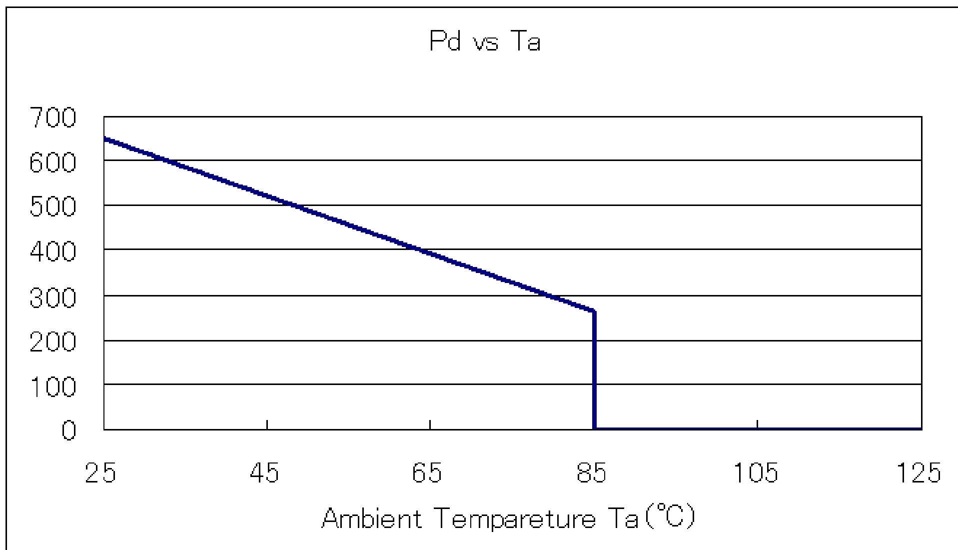


Evaluation Board (Unit: mm)

2. Power Dissipation vs. Ambient temperature

Board Mount (Tjmax=125℃)

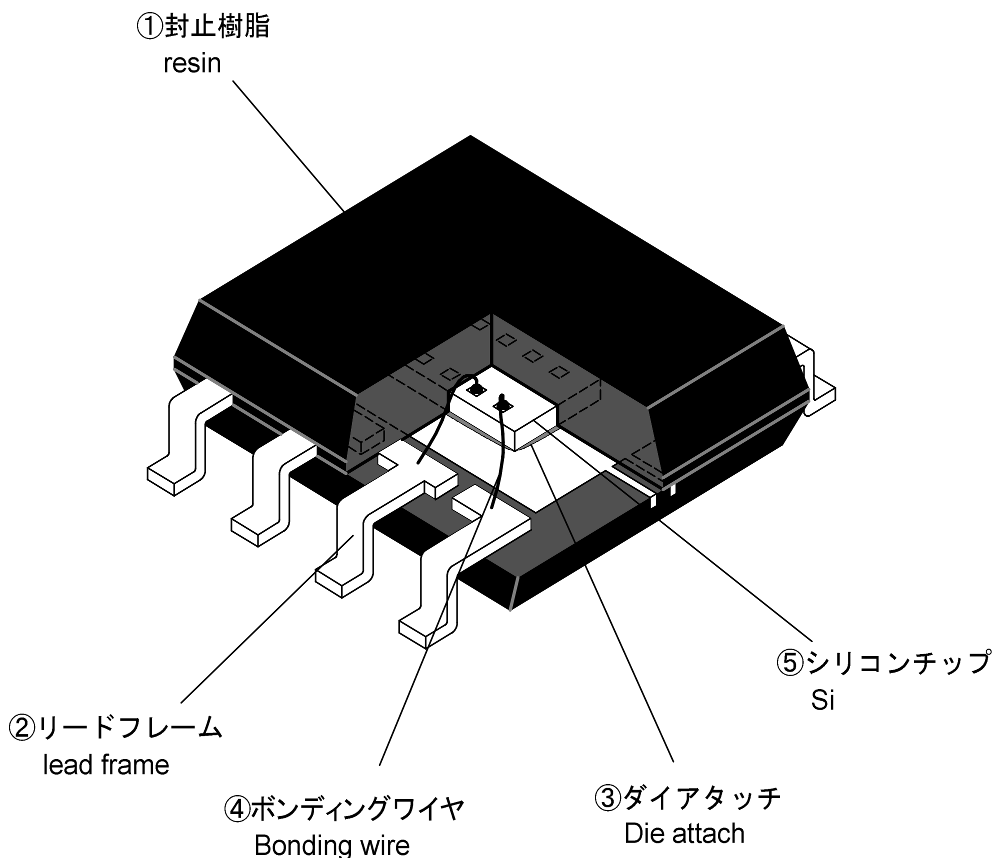
Ambient Temperature (℃)	Power Dissipation Pd (mW)	Thermal Resistance (℃/W)
25	650	153.85
85	260	



SOP-8構造図
SOP-8 Perspective

TOIREX

RoHS対応品
RoHS Compliance



項 目 Item		材 料 Material	備 考 Note
①	封止樹脂 Resin	エポキシ樹脂 Epoxy resin	難燃グレード/Flammability rating UL94V-0
②	リードフレーム Lead frame	銅系 Copper alloy	
	端子処理 Lead plating	鉛フリーはんだメッキ Lead(Pb) free solder plating	
③	ダイアタッチ Die attach	銀入りエポキシ Silver filled Epoxy	
④	ボンディングワイヤ Bonding wire	Au	
⑤	シリコンチップ Si	Si	

捺印表示 Marking	レーザー Laser marking